Surface Mount Schottky Power Rectifier

SMA Power Surface Mount Package

This device employs the Schottky Barrier principle in a large area metal-to-silicon power diode. State of the art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity diodes in surface mount applications where compact size and weight are critical to the system.

Features

- Small Compact Surface Mountable Package with J-Bent Leads
- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- Very Low Forward Voltage Drop
- Guard-ring for Stress Protection
- NRVBA Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable*
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 70 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

1

- Shipped in 12 mm tape, 5000 units per 13 inch reel
- Polarity: Cathode Lead Indicated by Polarity Band
- ESD Ratings:
 - ♦ Machine Model = C
 - ♦ Human Body Model = 3B



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SCHOTTKY BARRIER RECTIFIER 1.0 AMPERES 60 VOLTS



SMA CASE 403D

MARKING DIAGRAM



B16 = Specific Device Code A = Assembly Location**

Y = Year WW = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

**The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

ORDERING INFORMATION

Device	Package	Shipping [†]
MBRA160T3G	SMA (Pb-Free)	5,000 / Tape & Reel
NRVBA160T3G*	SMA (Pb-Free)	5,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	60	V	
Average Rectified Forward Current (At Rated V _R , T _C = 105°C)	lo	1.0	Α	
Average Rectified Forward Current (At Rated V _R , T _C = 70°C)	lo	2.1	Α	
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	60	Α	
Storage/Operating Case Temperature	T _{stg} , T _C	-55 to +150	°C	
Operating Junction Temperature (Note 1)	T _J	-55 to +150	°C	
Voltage Rate of Change (Rated V _R , T _J = 25°C)	dv/dt	10,000	V/µs	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The heat generated must be less than the thermal conductivity from Junction–to–Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit	
Thermal Resistance, Junction-to-Lead (Note 2) Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ hetaJL} \ R_{ hetaJA}$	35 86	°C/W	

^{2.} Mounted on 2" Square PC Board with 1" Square Total Pad Size, PC Board FR4.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Val	Unit	
Maximum Instantaneous Forward Voltage (Note 3)	V _F	T _J = 25°C	T _J = 125°C	V
$(I_F = 1.0 \text{ A})$		0.510	0.475	
Maximum Instantaneous Reverse Current	I _R	T _J = 25°C	T _J = 125°C	mA
(V _R = 60 V)		0.2	20	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Pulse Test: Pulse Width \leq 250 μ s, Duty Cycle \leq 2.0%.

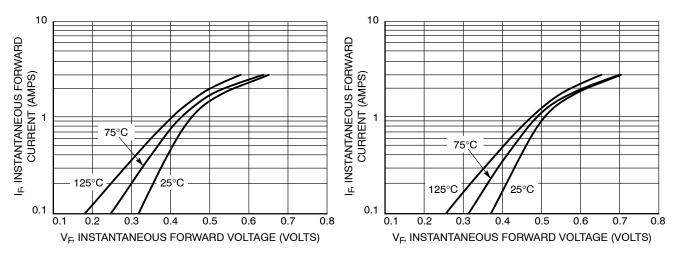


Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage

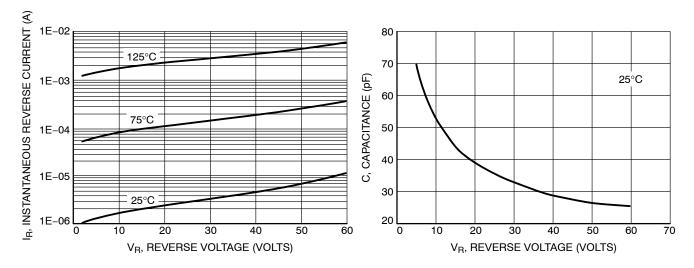


Figure 3. Typical Reverse Current

Figure 4. Typical Capacitance

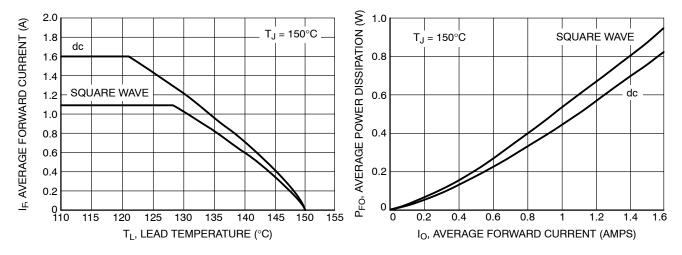


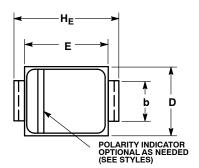
Figure 5. Current Derating - Junction-to-Lead

Figure 6. Forward Power Dissipation

PACKAGE DIMENSIONS

SMA

CASE 403D ISSUE H



NOTES

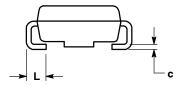
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M,
- 1982
- 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L.

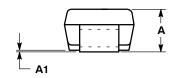
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.97	2.10	2.20	0.078	0.083	0.087
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.27	1.45	1.63	0.050	0.057	0.064
С	0.15	0.28	0.41	0.006	0.011	0.016
D	2.29	2.60	2.92	0.090	0.103	0.115
E	4.06	4.32	4.57	0.160	0.170	0.180
HE	4.83	5.21	5.59	0.190	0.205	0.220
L	0.76	1.14	1.52	0.030	0.045	0.060

STYLE 1

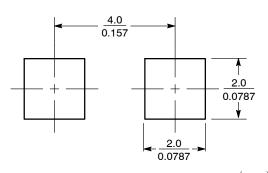
PIN 1. CATHODE (POLARITY BAND)

2. ANODE





SOLDERING FOOTPRINT*



SCALE 8:1 (mm/inches

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.